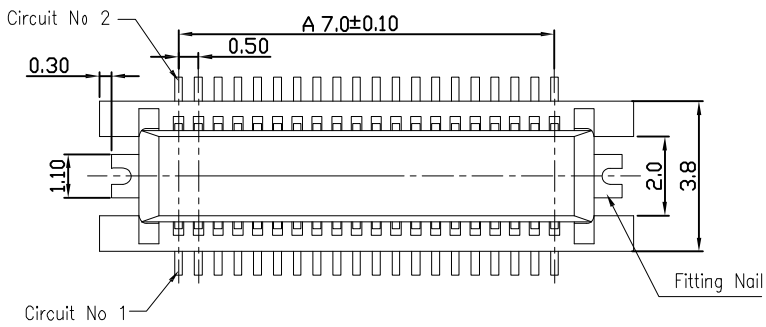
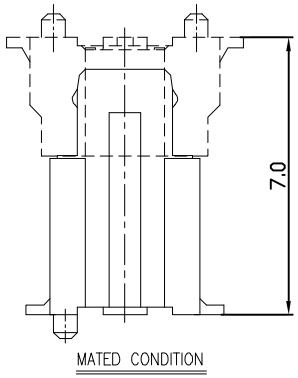
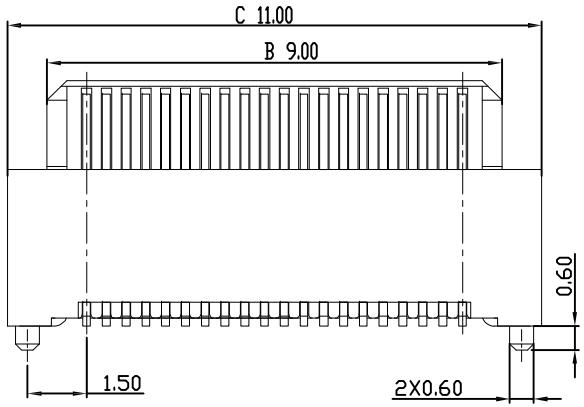
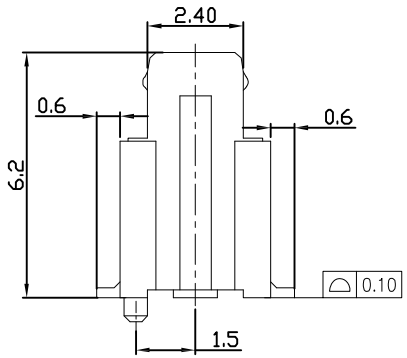


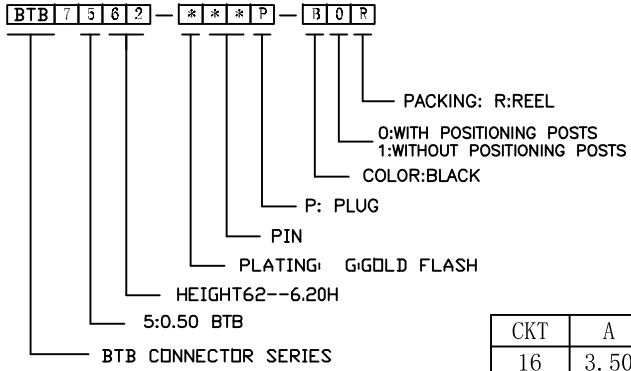


公座和母座装配后

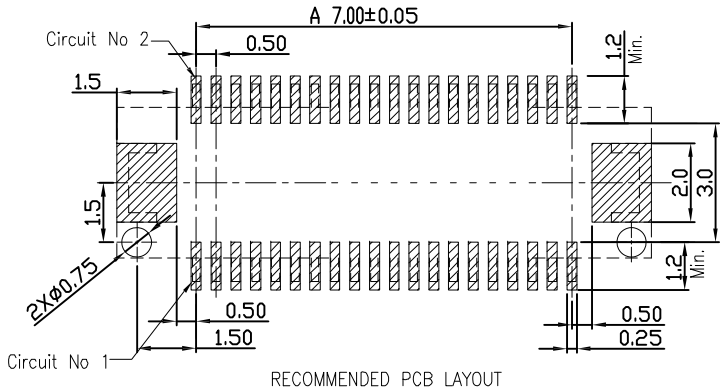
NOTES:
1. MATERIAL:
 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0;
 1.2 CONTACTS: COPPER ALLOY.
 1.3 FITTING NAIL: COPPER ALLOY.
2. FINISH:
 2.1 CONTACT:
  50u" MIN. NICKEL UNDERPLATING OVER ALL
  1:GOLD FLASH PLATING(1~3u") OVER ALL
  N:100~200u" MATT TIN PLATING OVER ALL
  D:30u" GOLD PLATING ON CONTACT AREA
 2.2 FITTING NAIL:
  50u" MIN. NICKEL UNDERPLATING OVER ALL
  100~200u" PURE MATT TIN PLATING OVER ALL
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.







CKT	A	B	C
16	3.50	5.50	7.50
20	4.50	6.50	8.50
30	7.00	9.00	11.00
40	9.50	11.50	13.50
50	12.00	14.00	16.00
60	14.50	16.50	18.50
70	17.00	19.00	21.00
80	19.50	21.50	23.50
100	24.50	26.50	28.50
120	29.50	31.50	33.50



RECOMMENDED PCB LAYOUT
GENERAL TOLORANCE ±0.05
WITH BOSS

TOLERANCE TABLE	
.0	±0.30
.00	±0.20
.000	±0.05

APPROVED:	DATE:	Ckmtw 深圳市灿科盟实业有限公司 CANKEMENG INDUSTRIAL CO.,LTD
CHECKED:	DATE:	TITLE: BTB0.5-30P 单槽公座 塑高6.2 立贴 (合高7.0mm)
DRAWN: YKX	DATE: 2026-7-7	PART.NO. Z-BTB0530P-M700
		UNIT mm SCALE free
		FILE NO. Ckmtw-BTB-B010 REV. A LXW0